



Material Content Data Sheet



Halogen-Free

Sales Product Name	IKB10N60T	Issued	11. August 2021
MA#	MA005342270		
Package	PG-TO263-3-2	Weight*	1558.28 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.641	0.04	0.04	411	411
chip_2	inorganic material	silicon	7440-21-3	1.169	0.08	0.08	750	750
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.51	19.54	195103	195357
wire	non noble metal	aluminium	7429-90-5	3.990	0.26	0.26	2561	2561
encapsulation	inorganic material	zinc oxide	1314-13-2	6.877	0.44		4413	
	miscellaneous	miscellaneous	-	27.506	1.77		17652	
	plastics	epoxy resin	-	103.149	6.62		66194	
	inorganic material	silicon dioxide	60676-86-0	550.128	35.29	44.12	353034	441293
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6197	6197
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.043			27	
	noble metal	silver	7440-22-4	0.053			34	
	non noble metal	lead	7439-92-1	2.042	0.13	0.13	1310	1371
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.15	35.20	351454	351912
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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